

Characterization of SU-8 Spin Coating over High Aspect Ratio Substrate Topography

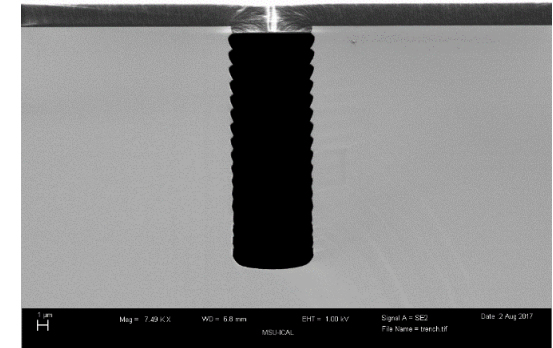
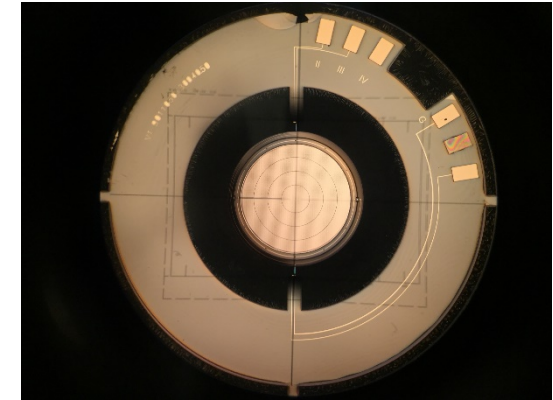
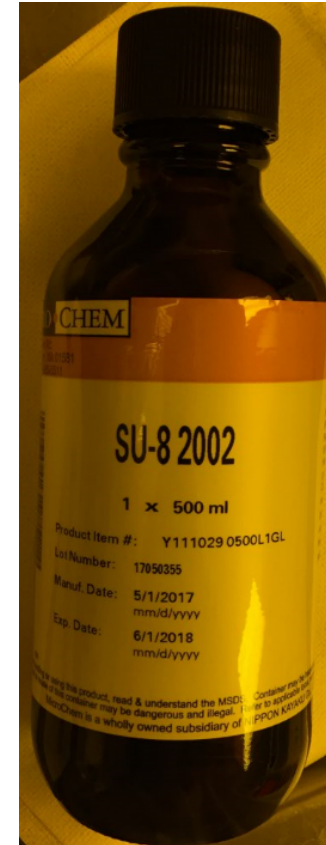
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Background

- What is SU-8?
- Role of SU-8 in MEMS fabrication
- Spin coating
- Complications from topography
- High aspect ratio topography



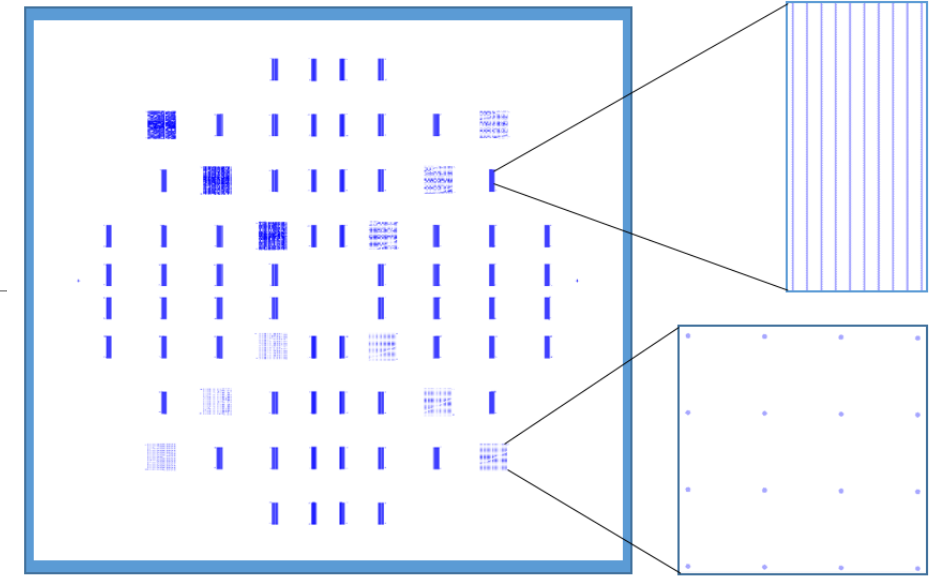
Objective

- Design and complete parametric study of SU-8 coating to help optimize MEMS mirror fabrication

- 1. Bridging
- 2. non-Planarity
- 3. Fill

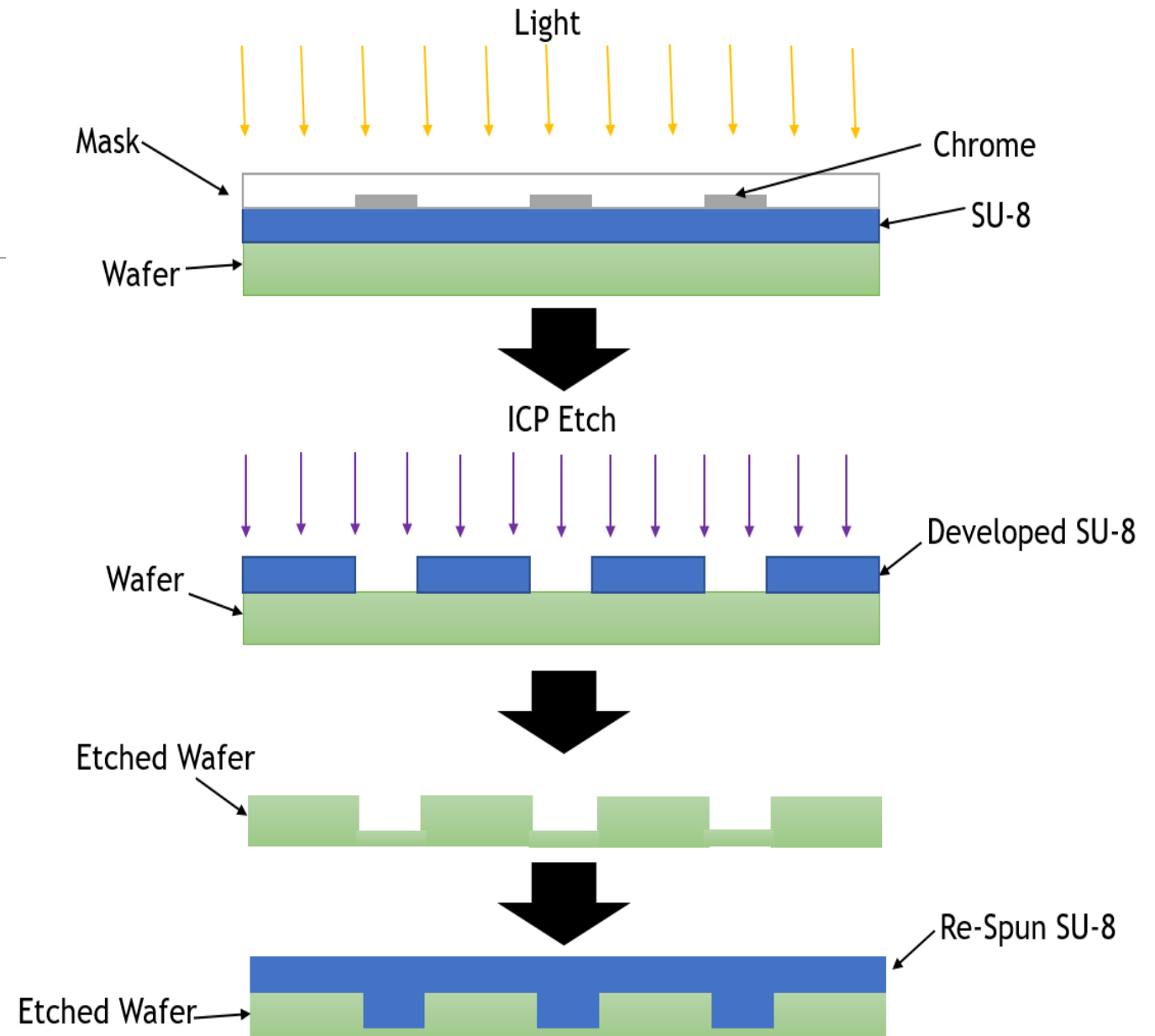
- Experimental parameters:

- Feature width
- Feature depth
- Feature radial location
- Feature angular orientation
- SU-8 viscosity
- Spin speed



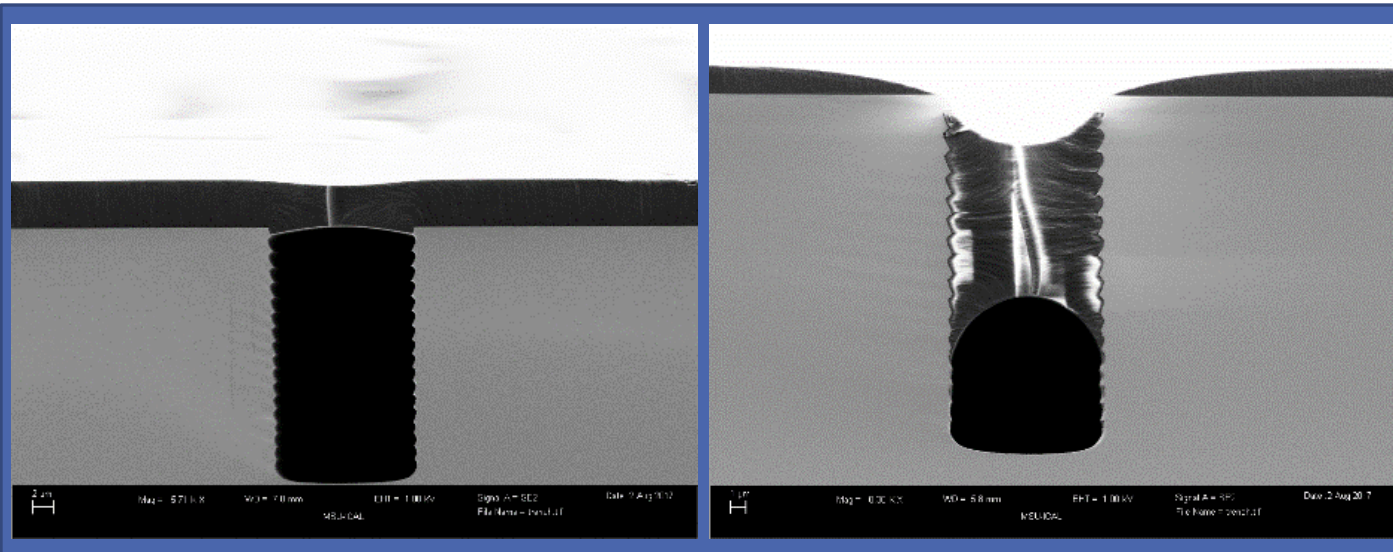
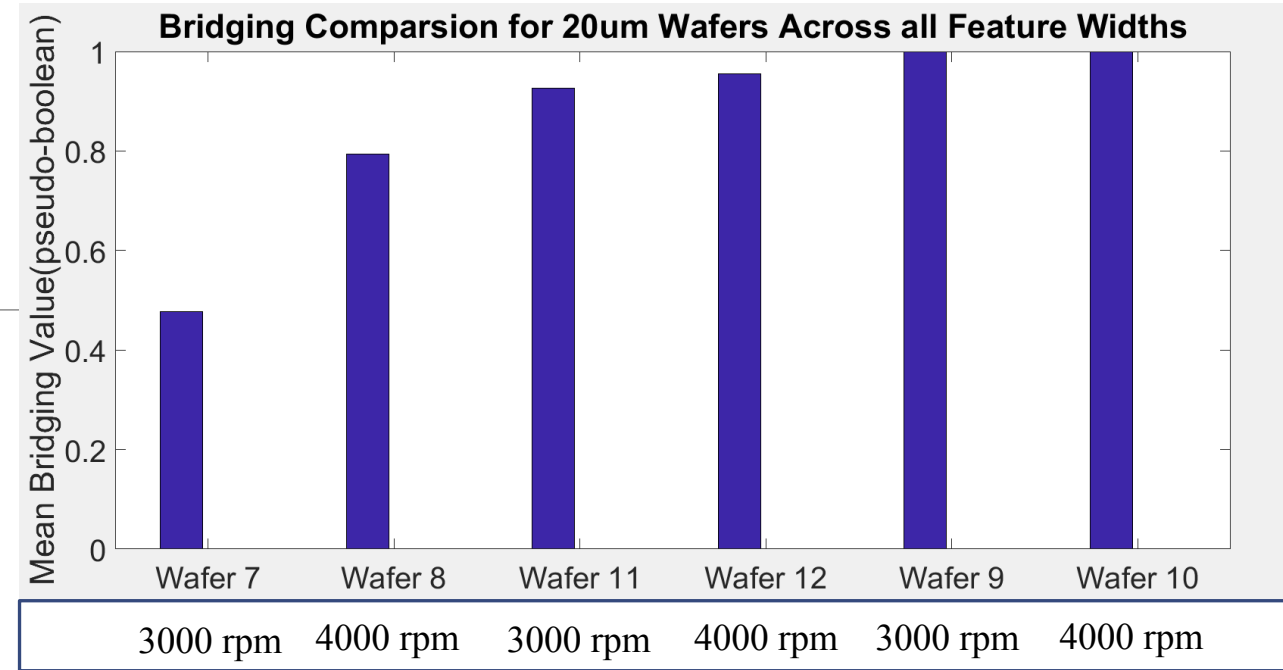
Methodology

1. Photolithography and ICP etch to create topography
2. Spin coating SU-8 over topography
3. Imaging with microscope and profilometer
4. Cleave across features and image with SEM for side profiles



Results-bridging

- Correlations- viscosity, spin speed, well width, and etch depth



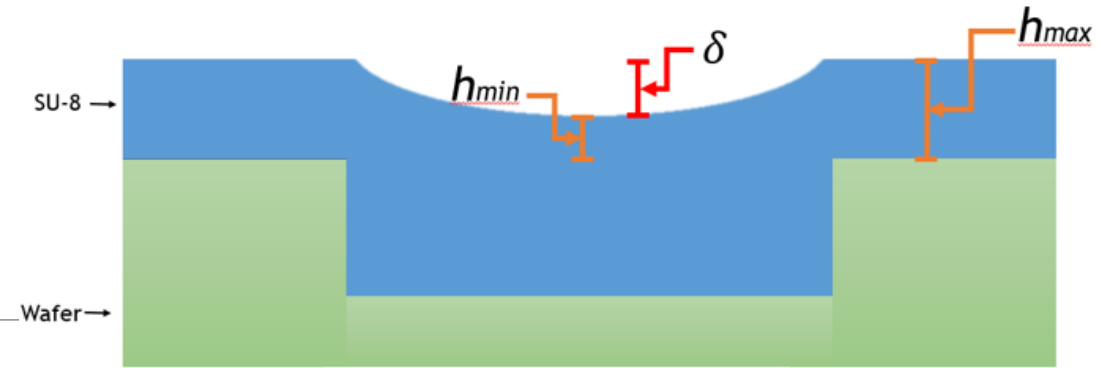
Increasing Viscosity



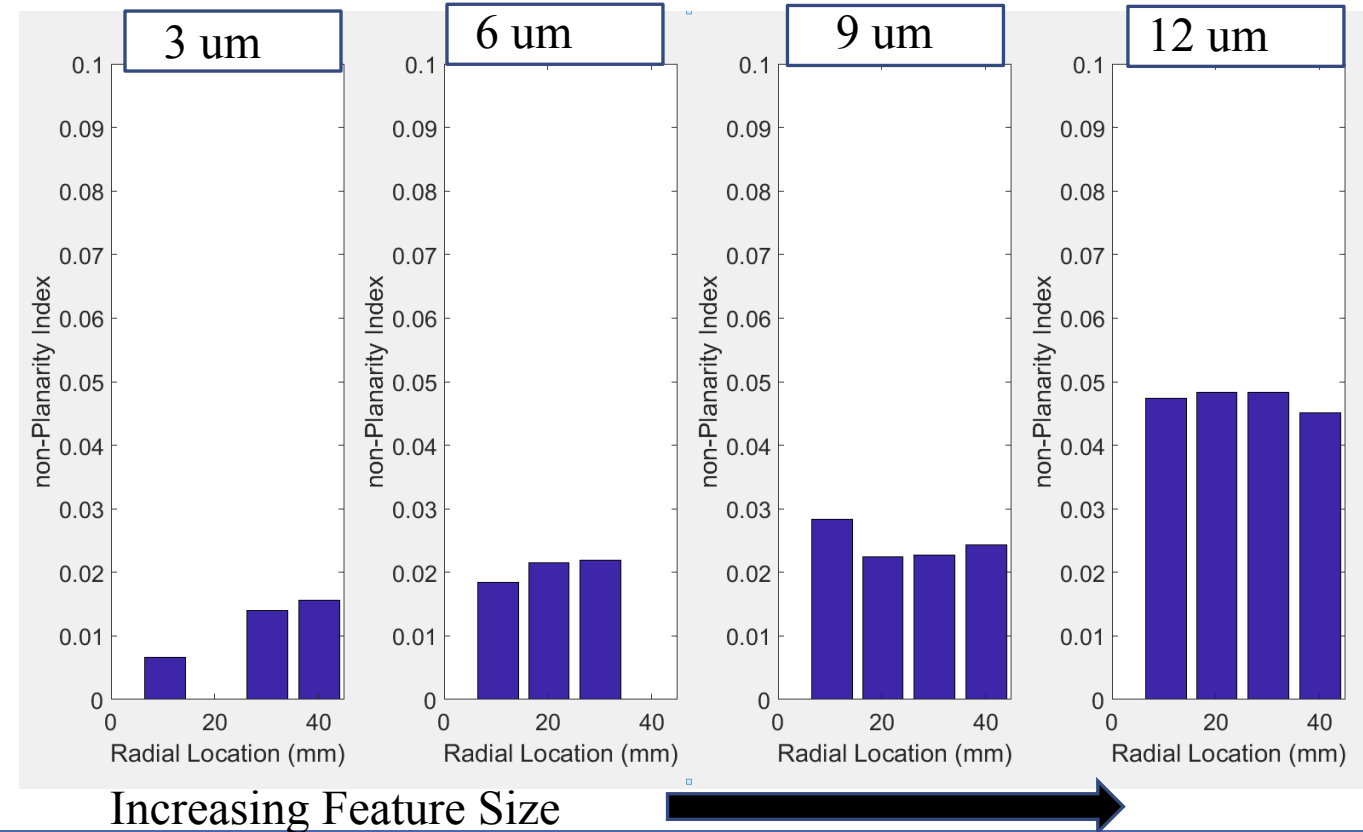
Results- non-planarity

Higher non-Planarity correlated with:

- Wider features
- Slower spin speeds
- Lower viscosity
- Deeper etch depths



$$\text{non-planarity} = \frac{\delta}{h_{max}}$$

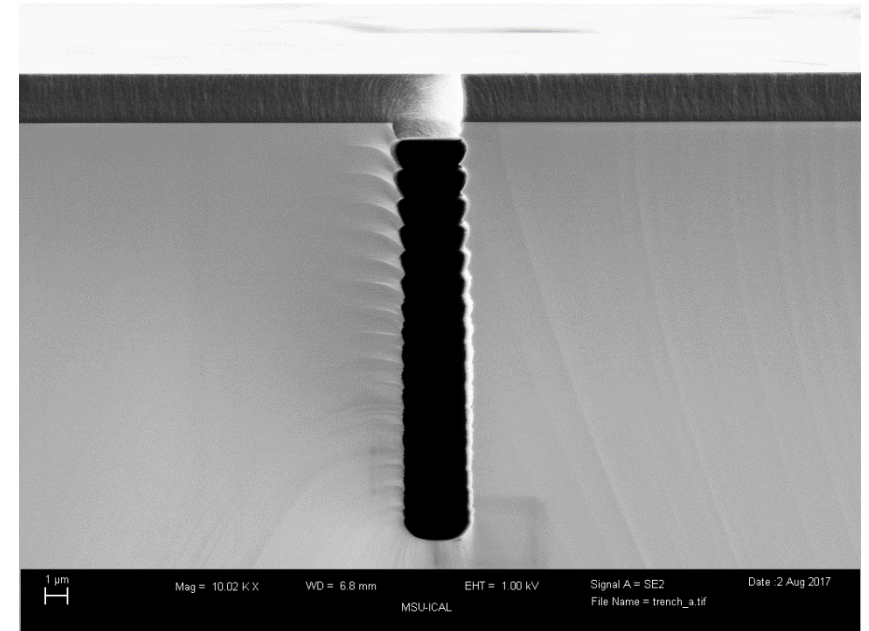
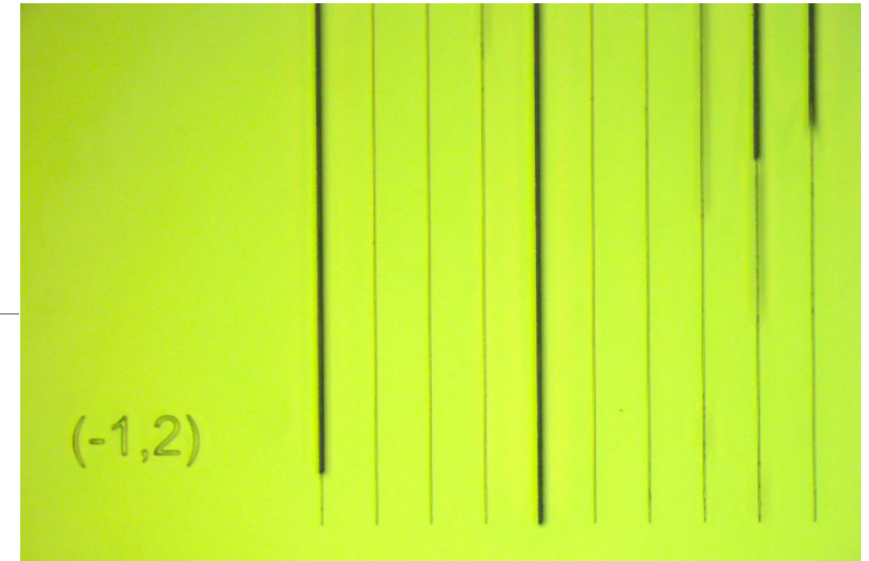


Conclusion

Spin coating over high aspect ratio substrate topography can be a highly sensitive process

Viscosity and spin speed are individually influential beyond the resultant film thickness

Future research



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